

TSMC01-614



September 29, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Ave.
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/055,095

01/23/02

C. C. Huang et al

"METHOD TO IMPROVE VIA OR CONTACT
HOLE PROFILE USING AN IN-SITU POLYMER
DEPOSITION AND STRIP PROCEDURE"

GRP. Art. Unit 2829

E. T. Pert

RESPONSE PATENT OFFICE ACTION

Dear Sir,

In response to the Office Action dated September 10, 2003, please amend the identified application for patent as follows:

The commissioner is hereby authorized to charge payment of any additional fees involved with added Claims and the like to Deposit Account No. 19-0033

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on February 10, 2004.

George O. Saile, Reg. No. 19,572

Signature George O. Saile

Date 2/10/04

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Amendments to the Claims begin on page **3**

Remarks begin on page 12.